

Vacuum produces high-quality soldering joints

“Vacuum plus” is a new, forward-looking system for optimising soldering joints that has been developed by SMT, the Wertheim-based specialist for thermal processes. As the name implies, any inclusions (bubbles) are eliminated in a vacuum chamber, which significantly improves the quality of the soldered products. This has been eagerly awaited, particularly by sensitive industries such as high-performance electronics, automotive, medical, aerospace and defence, in which soldering joint reliability has top priority.



“Vacuum plus”, which is an in-house development, is an autonomous module and can be integrated in an SMT Reflow Soldering System. Due to the modular design of the SMT Reflow Soldering Systems the new system can be retrofitted in existing machines without problems. “Vacuum plus” is inserted immediately after the peak zone, and can be enabled when required. The continuous reflow pass is then automatically changed to vacuum operation. The product is subjected to a vacuum for a short period during the soldering process. Inclusions in the soldering joint are reduced to a minimum, which improves the quality of the product significantly. Direct integration in the system gives the user a high degree of flexibility, and is significantly cheaper than a separate system.

For the first time SMT will present the „Vakuum plus“ at the exhibition „productronica“ in Munich; Halle A 4, Stand 159 from 10th - 13th November 2009.

Further information:

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